

C2220X393G5TACTU

Aliases (C2220X393G5TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 0.039 uF, 2%, 50 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	130 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	2220	
L	5.9mm +/-0.75mm	
W	5mm +/-0.4mm	
Т	1mm +/-0.15mm	
S	3.5mm MIN	
В	0.7mm +/-0.35mm	

V V	311111 1/ -0. 4 11111
Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm
Packaging Specifications	

Specifications		
Capacitance	0.039 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	2%	
Voltage DC	50 VDC	
Dielectric Withstanding Voltage	125 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	25.641 GOhms	

Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and (Applied (TCC)
Packaging Quantity	1000	Dissipation Factor

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